

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
KI YONG LEE		10/13/2008
SEUNG KWEON HA		10/13/2008
RECEIVING PARTY DATA		
Name:	HYNIX SEMICONDUCTOR INC.	
Street Address:	San 136-1, Ami-ri, Bubal-eub, Icheon-si	
City:	Kyoungki-do	
State/Country:	KOREA, REPUBLIC OF	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	12260231	
CORRESPONDENCE DATA		
Fax Number:	(312)427-6663	
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>		
Phone:	3124271300	
Email:	nicholas.kubacki@ladas.net	
Correspondent Name:	RICHARD J. STREIT	
Address Line 1:	LADAS & PARRY, 224 SOUTH MICHIGAN AVE.	
Address Line 4:	CHICAGO, ILLINOIS 60604	
ATTORNEY DOCKET NUMBER:	CU-6989 WWP/NK	
NAME OF SUBMITTER:	Woochoon W. Park	
Total Attachments: 2 source=cu6989assign#page1.tif source=cu6989assign#page2.tif		

CH \$40.00 12260231

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PATENT
REEL: 021755 FRAME: 0013



UNITED STATES OF AMERICA
ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNORS:

Name : Ki Yong LEE

Address: 219-414, Jang .wi 1-dong, Seongbuk-gu, Seoul, Korea

Name : Seung Kweon HA

Address: 111-1201, Hyundai I Park, Bongmyeong-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

ASSIGNEE:

Name : Hynix Semiconductor Inc.

Address : San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

METHOD FOR MANUFACTURING SEMICONDUCTOR PACKAGE HAVING IMPROVED
BUMP STRUCTURES

(TITLE)

and which is found in *(check one applicable item below)*

☒ U.S. patent application executed on even date herewith

☐ U.S. Application Serial No. _____ filed on _____

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;



ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

08.10.13

Date

08.10.13

Date

INVENTOR: Ki Yong LEE

INVENTOR: Seung Kweon HA

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